

Transport Properties of Patterned Magnetic Tunnel Junctions Using Lift-Off
Method

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Abstract

We develop a new process of fabricating MTJs which avoids the short circuit of the trilayers induced by the redeposit effect in etching process. The junction structures studied were prepared by UHV DC/RF magnetron sputtering. All MTJs have the same structure: Al (60)/Co₅₀Fe₅₀ (25)/Al + oxidation (1.2)/Ni₂₀Fe₈₀ (30)/Al (60), with all thickness given in nanometers. The thickness of AlO_x correspond to the effective barrier width determined by fitting I-V curve to Simmons Equation. The magnetization hysteresis (MH) loops are measured by a SQUID system at 298K. All MR measurements are taken at 180mV with 20×50 (μm^2) junction areas.